# 1-2355827-0 ACTIVE

#### Mezalok HSLF

TE Internal #: 1-2355827-0

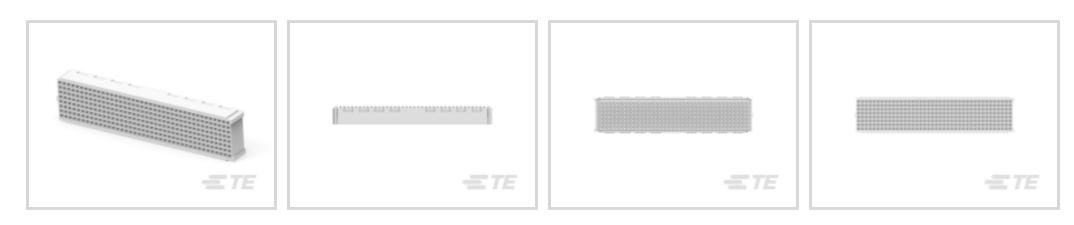
PCB Mount Receptacle, Vertical, Board-to-Board, 320 Position, 1.27 mm [.05 in] Centerline, Gold, Surface Mount - Solder Ball, Signal,

Mezalok HSLF

View on TE.com >



Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Receptacle

PCB Mount Orientation: Vertical
Connector System: Board-to-Board

Number of Positions: 320

Number of Rows: 8

### **Features**

### **Product Type Features**

| PCB Connector Assembly Type                    | PCB Mount Receptacle  |
|--|-----------------------|
| Connector System                               | Board-to-Board        |
| Sealable                                       | No                    |
| Connector & Contact Terminates To              | Printed Circuit Board |
| Configuration Features                         |                       |
| PCB Mount Orientation                          | Vertical              |
| Number of Positions                            | 320                   |
| Number of Rows                                 | 8                     |
| Board-to-Board Configuration                   | Parallel              |
| Body Features                                  |                       |
| Primary Product Color                          | Natural               |
| Contact Features                               |                       |
| Contact Mating Area Plating Material           | Gold                  |
| Contact Mating Area Plating Material Thickness | 50 μm[50 μin]         |
| Contact Type                                   | Socket                |
| Contact Current Rating (Max)                   | 1.5 A                 |

**Termination Features** 



| Termination Method to Printed Circuit Board | Surface Mount - Solder Ball |
|---|-----------------------------|
| Mechanical Attachment                       |                             |
| Mating Alignment                            | With                        |
| Mating Alignment Type                       | Keyed                       |
| PCB Mount Retention                         | Without                     |
| PCB Mount Alignment                         | Without                     |
| Connector Mounting Type                     | Board Mount                 |
| Housing Features                            |                             |
| Centerline (Pitch)                          | 1.27 mm[.05 in]             |
| Housing Material                            | LCP                         |
| Dimensions                                  |                             |
| Row-to-Row Spacing                          | 1.27 mm[.05 in]             |
| Stack Height                                | 18 mm[.709 in]              |
| Usage Conditions                            |                             |
| Operating Temperature Range                 | -55 – 125 °C[-67 – 257 °F]  |
| Operation/Application                       |                             |
| Circuit Application                         | Signal                      |
| Industry Standards                          |                             |
| UL Flammability Rating                      | UL 94V-0                    |
| Packaging Features                          |                             |
| Packaging Type                              | Tape & Reel                 |
|   |                             |

# **Product Compliance**

For compliance documentation, visit the product page on TE.com>

| EU RoHS Directive 2011/65/EU                  | Compliant  |
|---|--|
| EU ELV Directive 2000/53/EC                   | Not Yet Reviewed   |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold  |
| EU REACH Regulation (EC) No. 1907/2006        | Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JAN 2021 (211) Does not contain REACH SVHC |
| Halogen Content                               | Not Yet Reviewed for halogen content   |



#### Solder Process Capability

Not reviewed for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

# **Compatible Parts**



# Also in the Series | Mezalok HSLF



# **Customers Also Bought**

















#### **Documents**

### **Product Drawings**

Mezalok, LF SKT, 320 p, 18 mm, 50 Au, LF

English

#### **CAD Files**

3D PDF

3D

**Customer View Model** 

ENG\_CVM\_CVM\_1-2355827-0\_1.2d\_dxf.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_1-2355827-0\_1.3d\_igs.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_1-2355827-0\_1.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

## **Product Specifications**

**Product Specification** 

English

**Product Specification** 

English